Materials Declaration

Package	LQFP_EP
Body Size	20 X 20 X 1.4
LeadCount	144
Option	Pb-free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Silica	86.91	8.89 E-01	676187
Epoxy and Phenol resin	12.78	1.31 E-01	99432
Carbon black	0.31	3.17 E-03	2412
Subtotal		1.02 E+00	778030

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	1.87 E-01	142469
Ni	3	5.84 E-03	4443
Si	0.65	1.27 E-03	963
Mg	0.15	2.92 E-04	222
Subtotal		1.95 E-01	148097

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	1.93 E-03	1467

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	2.60 E-02	19774

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	7.38 E-04	561

Chip

	% of Chip	Weight (g)	PPM
Si	100	6.00 E-02	45631

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag	72.4	6.13 E-03	4662
Epoxy compound	18.1	1.53 E-03	1166
Anhydrides	6.8	5.75 E-04	437
Polymeric material	2.7	2.29 E-04	174
Subtotal		8.47 E-03	6439

Package Totals

Weight (g)	PPM
1.31 E+00	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA 3051/3052. ICP-OES
Cd	Not Detected	EPA 3051/3052. ICP-OES
Hg	Not Detected	EPA 3051/3052. ICP-OES
Cr+6	Not Detected	EPA 3060A & 7196A. UV-VIS
PBB	Not Detected	EPA 3550C/3540C. GC/MS
PBDE	Not Detected	EPA 3550C/3540C. GC/MS

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	USEPA 3052. ICP-OES
Cd	Not Detected	USEPA 3052. ICP-OES
Hg	Not Detected	USEPA 3052. ICP-OES
Cr+6	Not Detected	EPA 3060A & 7196A. UV-VIS
PBB	Not Detected	USEPA 3550C/3540C. GC/MS
PBDE	Not Detected	USEPA 3550C/3540C. GC/MS

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ADI Proprietary

Materials Declaration

Package	LQFP_EP
Body Size	20 X 20 X 1.4
LeadCount	144
Option	SnPb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Silica	86.91	8.89 E-01	676187
Epoxy and Phenol resin	12.78	1.31 E-01	99432
Carbon black	0.31	3.17 E-03	2412
Subtotal		1.02 E+00	778030

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	1.87 E-01	142469
Ni	3	5.84 E-03	4443
Si	0.65	1.27 E-03	963
Mg	0.15	2.92 E-04	222
Subtotal		1.95 E-01	148097

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	1.93 E-03	1467

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	2.21 E-02	16808
Pb	15	3.90 E-03	2966
Subtotal		2.60 E-02	19774

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	7.38 E-04	561

Chip

	% of Chip	Weight (g)	PPM
Si	100	6.00 E-02	45631

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag	72.4	6.13 E-03	4662
Epoxy compound	18.1	1.53 E-03	1166
Anhydrides	6.79	5.75 E-04	437
Polymeric material	2.71	2.29 E-04	174
Subtotal		8.47 E-03	6439

Package Totals

Weight (g)	PPM
1.31 E+00	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA 3051/3052. ICP-OES
Cd	Not Detected	EPA 3051/3052. ICP-OES
Hg	Not Detected	EPA 3051/3052. ICP-OES
Cr+6	Not Detected	EPA 3060A & 7196A. UV-VIS
PBB	Not Detected	EPA 3550C/3540C. GC/MS
PBDE	Not Detected	EPA 3550C/3540C. GC/MS

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	USEPA 3052. ICP-OES
Cd	Not Detected	USEPA 3052. ICP-OES
Hg	Not Detected	USEPA 3052. ICP-OES
Cr+6	Not Detected	EPA 3060A & 7196A. UV-VIS
PBB	Not Detected	USEPA 3550C/3540C. GC/MS
PBDE	Not Detected	USEPA 3550C/3540C. GC/MS

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